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Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	13
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 4x8b
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Through Hole
Package / Case	18-DIP (0.300", 7.62mm)
Supplier Device Package	18-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c712-04-p

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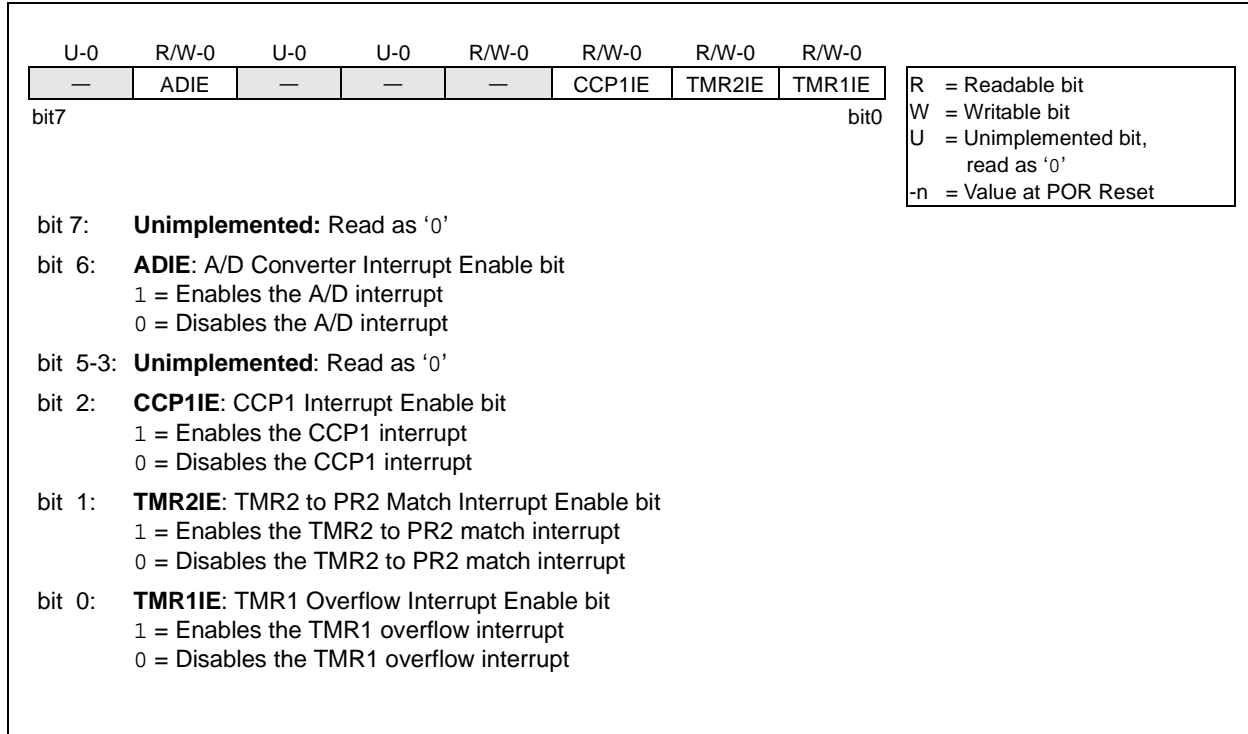
PIC16C712/716

2.2.2.4 PIE1 Register

This register contains the individual enable bits for the peripheral interrupts.

Note: Bit PEIE (INTCON<6>) must be set to enable any peripheral interrupt.

FIGURE 2-7: PIE1 REGISTER (ADDRESS 8Ch)



PIC16C712/716

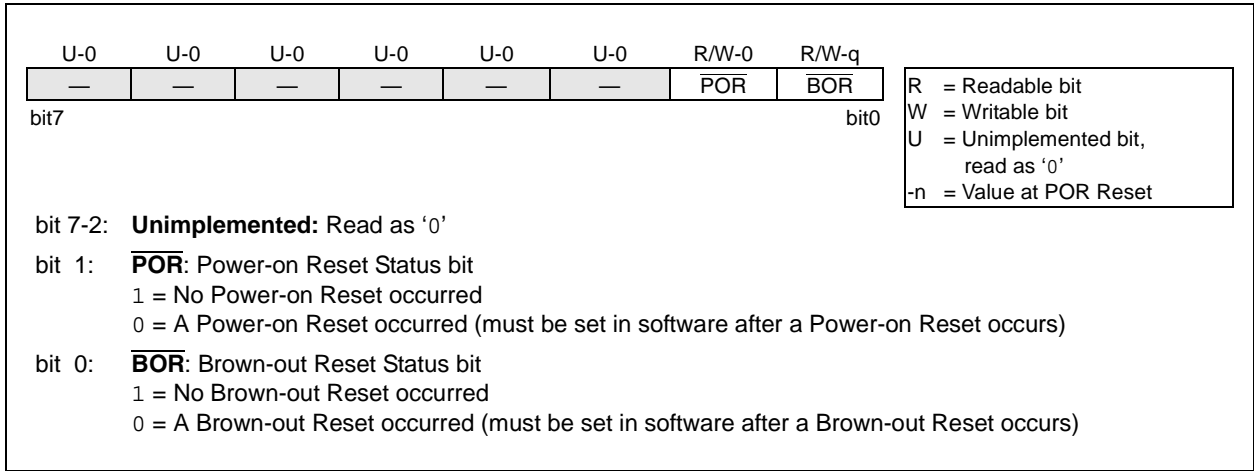
2.2.2.6 PCON Register

The Power Control (PCON) register contains a flag bit to allow differentiation between a Power-on Reset (POR) to an external MCLR Reset or WDT Reset. These devices contain an additional bit to differentiate a Brown-out Reset condition from a Power-on Reset condition.

Note: If the BODEN Configuration bit is set, BOR is '1' on Power-on Reset. If the BODEN Configuration bit is clear, BOR is unknown on Power-on Reset.

The $\overline{\text{BOR}}$ Status bit is a "don't care" and is not necessarily predictable if the brown-out circuit is disabled (the BODEN Configuration bit is clear). $\overline{\text{BOR}}$ must then be set by the user and checked on subsequent resets to see if it is clear, indicating a brown-out has occurred.

FIGURE 2-9: PCON REGISTER (ADDRESS 8Eh)



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FIGURE 3-1: BLOCK DIAGRAM OF RA3:RA0

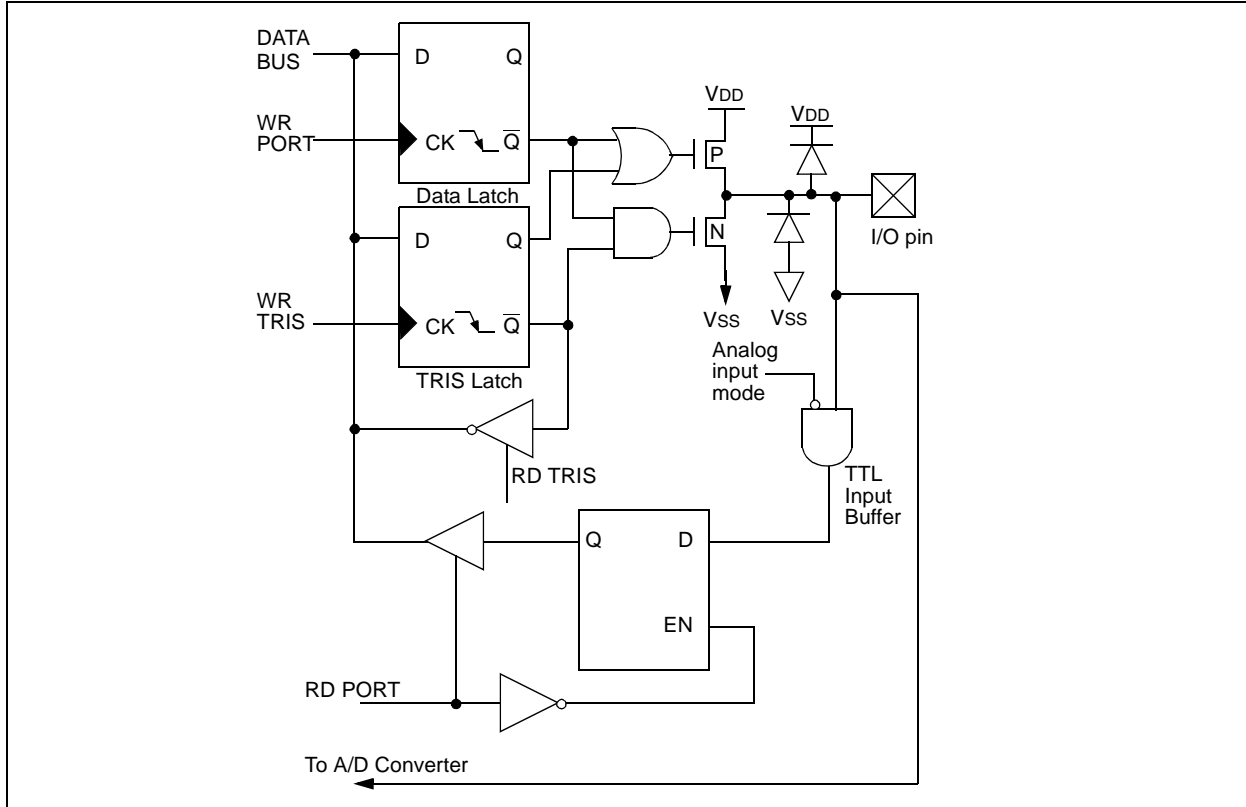
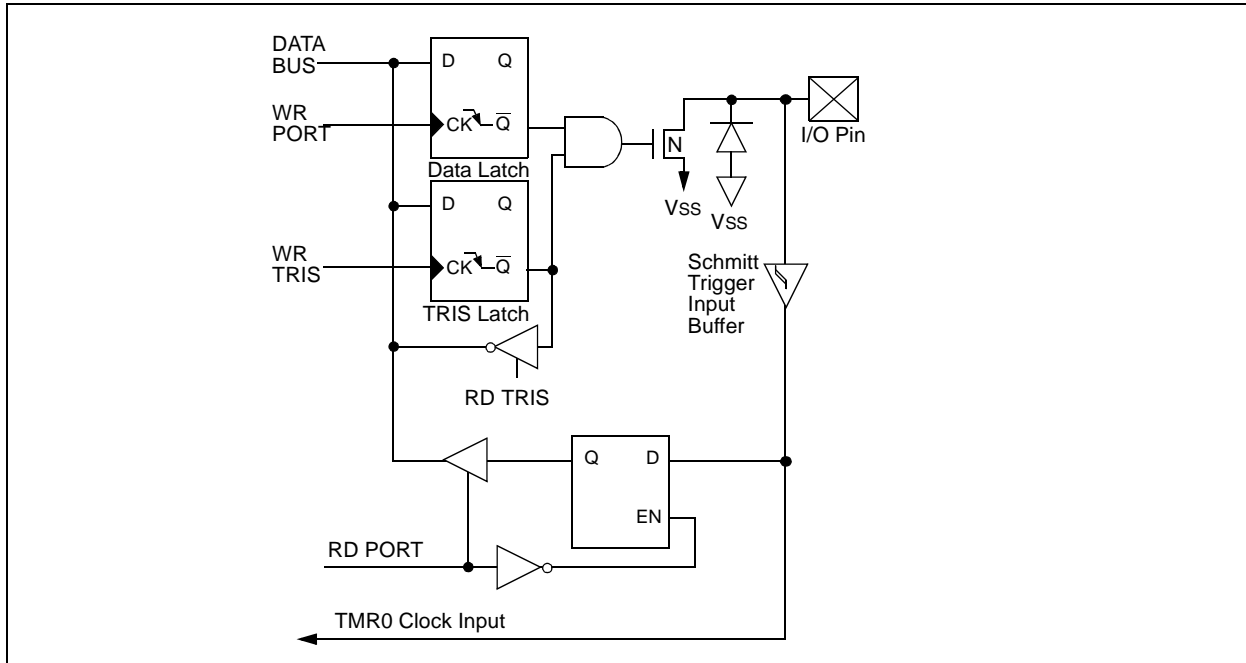


FIGURE 3-2: BLOCK DIAGRAM OF RA4/T0CKI PIN



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3.2 PORTB and the TRISB Register

PORTB is an 8-bit wide bidirectional port. The corresponding data direction register is TRISB. Setting a TRISB bit (= 1) will make the corresponding PORTB pin an input, (i.e., put the corresponding output driver in a High-Impedance mode). Clearing a TRISB bit (= 0) will make the corresponding PORTB pin an output, (i.e., put the contents of the output latch on the selected pin).

Each of the PORTB pins has a weak internal pull-up. A single control bit can turn on all the pull-ups. This is performed by clearing bit $\overline{\text{RBPU}}$ (OPTION_REG<7>). The weak pull-up is automatically turned off when the port pin is configured as an output. The pull-ups are disabled on a Power-on Reset.

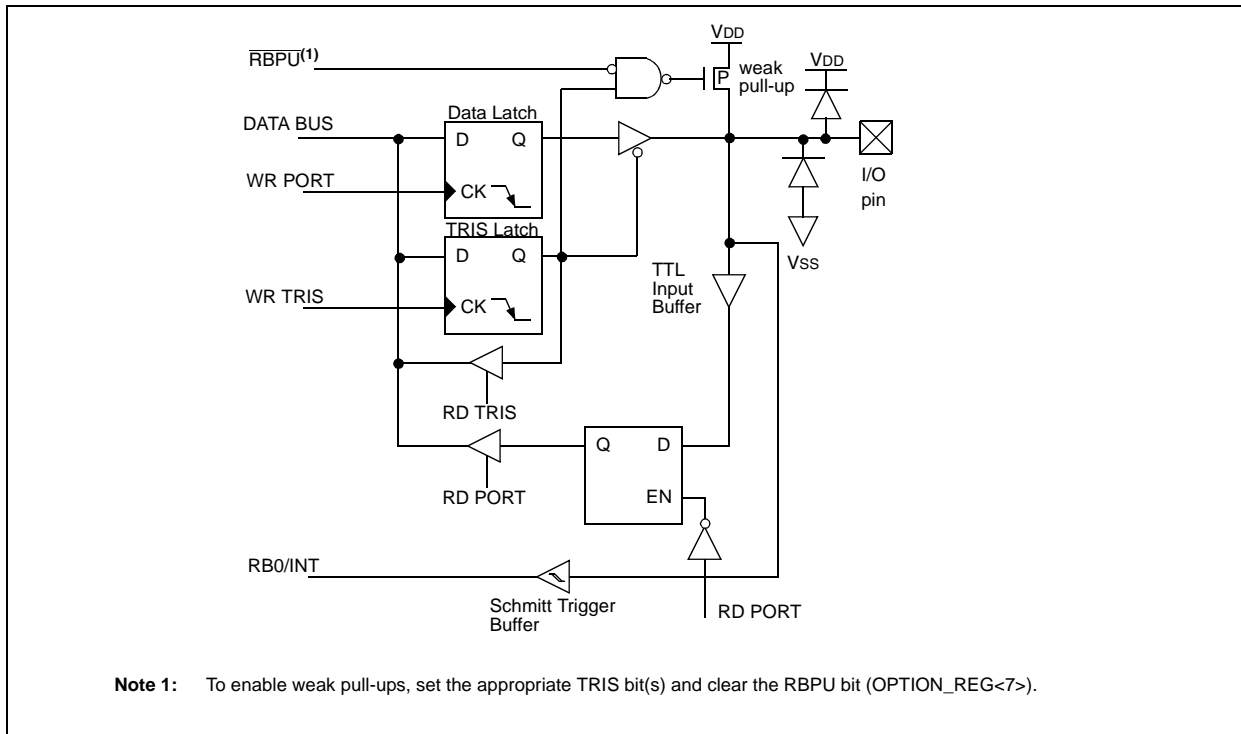
EXAMPLE 3-2: INITIALIZING PORTB

```
BCF STATUS, RP0 ;
CLRF PORTB      ; Initialize PORTB by
                 ; clearing output
                 ; data latches

BSF STATUS, RP0 ; Select Bank 1
MOVLW 0xCF      ; Value used to
                 ; initialize data
                 ; direction

MOVWF TRISB     ; Set RB<3:0> as inputs
                 ; RB<5:4> as outputs
                 ; RB<7:6> as inputs
```

FIGURE 3-3: BLOCK DIAGRAM OF RB0 PIN



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TABLE 3-4: SUMMARY OF REGISTERS ASSOCIATED WITH PORTB

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets
06h	PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx xxxx	uuuu uuuu
86h	TRISB	PORTB Data Direction Register								1111 1111	1111 1111
81h	OPTION_REG	$\overline{\text{RBPU}}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111

Legend: x = unknown, u = unchanged. Shaded cells are not used by PORTB.

4.0 TIMER0 MODULE

The Timer0 module timer/counter has the following features:

- 8-bit timer/counter
- Readable and writable
- Internal or external clock select
- Edge select for external clock
- 8-bit software programmable prescaler
- Interrupt on overflow from FFh to 00h

Figure 4-1 is a simplified block diagram of the Timer0 module.

Additional information on timer modules is available in the PIC[®] Mid-Range Reference Manual, (DS33023).

4.1 Timer0 Operation

Timer0 can operate as a timer or as a counter.

Timer mode is selected by clearing bit T0CS (OPTION_REG<5>). In timer mode, the Timer0 module will increment every instruction cycle (without prescaler). If the TMR0 register is written, the increment is inhibited for the following two instruction cycles. The user can work around this by writing an adjusted value to the TMR0 register.

Counter mode is selected by setting bit T0CS (OPTION_REG<5>). In Counter mode, Timer0 will increment on every rising or falling edge of pin RA4/T0CKI. The incrementing edge is determined by the Timer0 Source Edge Select bit T0SE (OPTION_REG<4>). Clearing bit T0SE selects the rising edge. Restrictions on the external clock input are discussed below.

When an external clock input is used for Timer0, it must meet certain requirements. The requirements ensure the external clock can be synchronized with the internal phase clock (Tosc). Also, there is a delay in the actual incrementing of Timer0 after synchronization.

Additional information on external clock requirements is available in the PIC[®] Mid-Range Reference Manual, (DS33023).

4.2 Prescaler

An 8-bit counter is available as a prescaler for the Timer0 module or as a postscaler for the Watchdog Timer, respectively (Figure 4-2). For simplicity, this counter is being referred to as “prescaler” throughout this data sheet. Note that there is only one prescaler available, which is mutually exclusively shared between the Timer0 module and the Watchdog Timer. Thus, a prescaler assignment for the Timer0 module means that there is no prescaler for the Watchdog Timer and vice-versa.

The prescaler is not readable or writable.

The PSA and PS2:PS0 bits (OPTION_REG<3:0>) determine the prescaler assignment and prescale ratio.

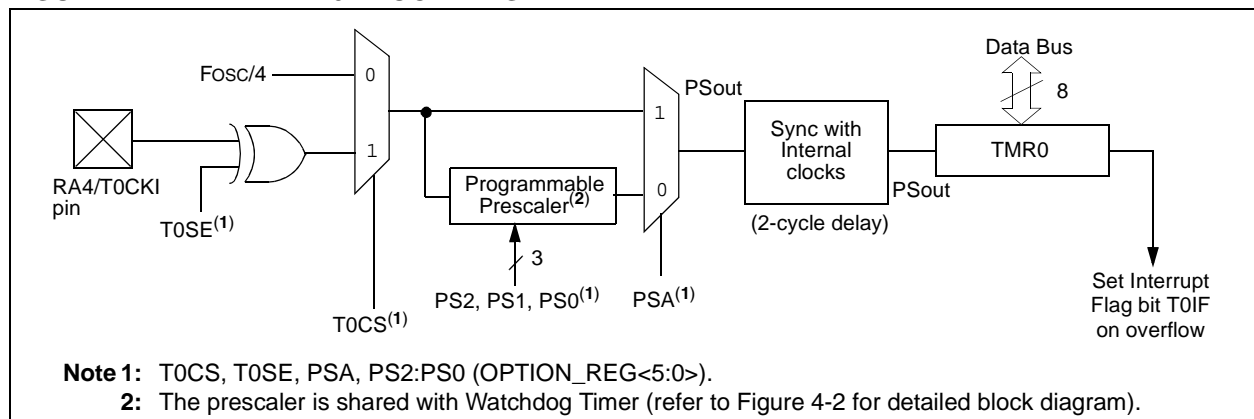
Clearing bit PSA will assign the prescaler to the Timer0 module. When the prescaler is assigned to the Timer0 module, prescale values of 1:2, 1:4, ..., 1:256 are selectable.

Setting bit PSA will assign the prescaler to the Watchdog Timer (WDT). When the prescaler is assigned to the WDT, prescale values of 1:1, 1:2, ..., 1:128 are selectable.

When assigned to the Timer0 module, all instructions writing to the TMR0 register (e.g., CLRF 1, MOVWF 1, BSF 1, x....etc.) will clear the prescaler. When assigned to WDT, a CLRWDT instruction will clear the prescaler along with the WDT.

Note: Writing to TMR0 when the prescaler is assigned to Timer0 will clear the prescaler count, but will not change the prescaler assignment.

FIGURE 4-1: TIMER0 BLOCK DIAGRAM



NOTES:

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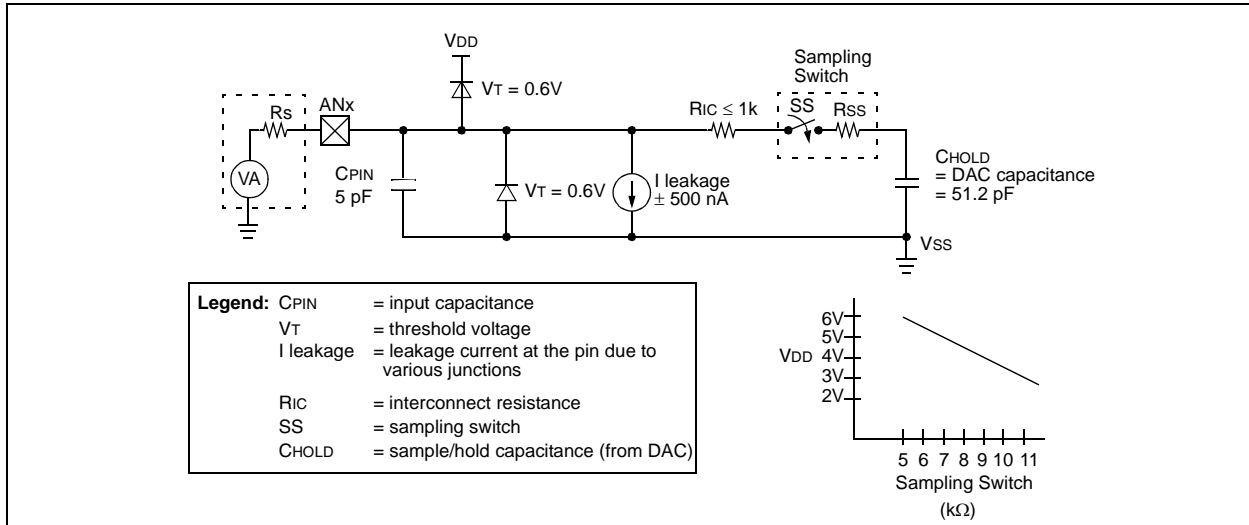
8.1 A/D Acquisition Requirements

For the A/D converter to meet its specified accuracy, the Charge Holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 8-4. The source impedance (R_s) and the internal sampling switch (R_{SS}) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (R_{SS}) impedance varies over the device voltage (V_{DD}). The source impedance affects the offset voltage at the analog input (due to pin leakage current). **The maximum recommended impedance for analog sources is 10 k Ω .** After the analog input channel is selected (changed) this acquisition must be done before the conversion can be started.

To calculate the minimum acquisition time, T_{ACQ} , see the PIC[®] Mid-Range Reference Manual, (DS33023). This equation calculates the acquisition time to within 1/2 LSB error (512 steps for the A/D). The 1/2 LSB error is the maximum error allowed for the A/D to meet its specified accuracy.

Note: When the conversion is started, the hold-ing capacitor is disconnected from the input pin.

FIGURE 8-4: ANALOG INPUT MODEL



9.2 Oscillator Configurations

9.2.1 OSCILLATOR TYPES

The PIC16CXXX can be operated in four different Oscillator modes. The user can program two Configuration bits (FOSC1 and FOSC0) to select one of these four modes:

- LP Low-Power Crystal
- XT Crystal/Resonator
- HS High-Speed Crystal/Resonator
- RC Resistor/Capacitor

9.2.2 CRYSTAL OSCILLATOR/CERAMIC RESONATORS

In XT, LP or HS modes, a crystal or ceramic resonator is connected to the OSC1/CLKIN and OSC2/CLKOUT pins to establish oscillation (Figure 9-2). The PIC16CXXX oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications. When in XT, LP or HS modes, the device can have an external clock source to drive the OSC1/CLKIN pin (Figure 9-3).

FIGURE 9-2: CRYSTAL/CERAMIC RESONATOR OPERATION (HS, XT OR LP OSC CONFIGURATION)

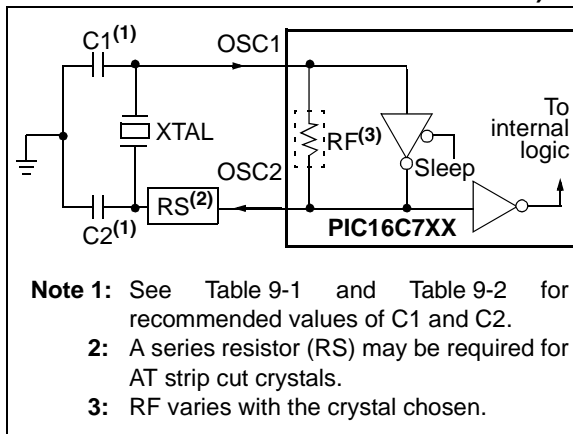


FIGURE 9-3: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP OSC CONFIGURATION)

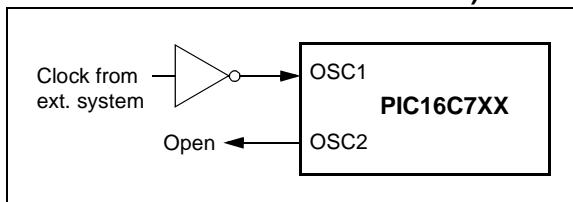


TABLE 9-1: CERAMIC RESONATORS

Ranges Tested:			
Mode	Freq	OSC1	OSC2
XT	455 kHz	68-100 pF	68-100 pF
	2.0 MHz	15-68 pF	15-68 pF
	4.0 MHz	15-68 pF	15-68 pF
HS	8.0 MHz	10-68 pF	10-68 pF
	16.0 MHz	10-22 pF	10-22 pF

These values are for design guidance only. See notes at bottom of page.

TABLE 9-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR

Osc Type	Crystal Freq	Cap. Range C1	Cap. Range C2
LP	32 kHz	33 pF	33 pF
	200 kHz	15 pF	15 pF
XT	200 kHz	47-68 pF	47-68 pF
	1 MHz	15 pF	15 pF
	4 MHz	15 pF	15 pF
HS	4 MHz	15 pF	15 pF
	8 MHz	15-33 pF	15-33 pF
	20 MHz	15-33 pF	15-33 pF

These values are for design guidance only. See notes at bottom of page.

- Note 1:** Recommended values of C1 and C2 are identical to the ranges tested (Table 9-1).
2: Higher capacitance increases the stability of the oscillator, but also increases the start-up time.
3: Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components.
4: Rs may be required in HS mode, as well as XT mode to avoid overdriving crystals with low drive level specification.

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9.16 In-Circuit Serial Programming™

PIC16CXXX microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data, and three other lines for power, ground and the programming voltage. This allows customers to manufacture boards with unprogrammed devices, and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

For complete details on serial programming, please refer to the In-Circuit Serial Programming™ (ICSP™) Guide, (DS30277).

11.0 DEVELOPMENT SUPPORT

The PIC[®] microcontrollers are supported with a full range of hardware and software development tools:

- Integrated Development Environment
 - MPLAB[®] IDE Software
- Assemblers/Compilers/Linkers
 - MPASM[™] Assembler
 - MPLAB C18 and MPLAB C30 C Compilers
 - MPLINK[™] Object Linker/
MPLIB[™] Object Librarian
 - MPLAB ASM30 Assembler/Linker/Library
- Simulators
 - MPLAB SIM Software Simulator
- Emulators
 - MPLAB ICE 2000 In-Circuit Emulator
 - MPLAB ICE 4000 In-Circuit Emulator
- In-Circuit Debugger
 - MPLAB ICD 2
- Device Programmers
 - PICSTART[®] Plus Development Programmer
 - MPLAB PM3 Device Programmer
- Low-Cost Demonstration and Development Boards and Evaluation Kits

11.1 MPLAB Integrated Development Environment Software

The MPLAB IDE software brings an ease of software development previously unseen in the 8/16-bit microcontroller market. The MPLAB IDE is a Windows[®] operating system-based application that contains:

- A single graphical interface to all debugging tools
 - Simulator
 - Programmer (sold separately)
 - Emulator (sold separately)
 - In-Circuit Debugger (sold separately)
- A full-featured editor with color-coded context
- A multiple project manager
- Customizable data windows with direct edit of contents
- High-level source code debugging
- Visual device initializer for easy register initialization
- Mouse over variable inspection
- Drag and drop variables from source to watch windows
- Extensive on-line help
- Integration of select third party tools, such as HI-TECH Software C Compilers and IAR C Compilers

The MPLAB IDE allows you to:

- Edit your source files (either assembly or C)
- One touch assemble (or compile) and download to PIC MCU emulator and simulator tools (automatically updates all project information)
- Debug using:
 - Source files (assembly or C)
 - Mixed assembly and C
 - Machine code

MPLAB IDE supports multiple debugging tools in a single development paradigm, from the cost-effective simulators, through low-cost in-circuit debuggers, to full-featured emulators. This eliminates the learning curve when upgrading to tools with increased flexibility and power.

11.11 PICSTART Plus Development Programmer

The PICSTART Plus Development Programmer is an easy-to-use, low-cost, prototype programmer. It connects to the PC via a COM (RS-232) port. MPLAB Integrated Development Environment software makes using the programmer simple and efficient. The PICSTART Plus Development Programmer supports most PIC devices in DIP packages up to 40 pins. Larger pin count devices, such as the PIC16C92X and PIC17C76X, may be supported with an adapter socket. The PICSTART Plus Development Programmer is CE compliant.

11.12 Demonstration, Development and Evaluation Boards

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart® battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Check the Microchip web page (www.microchip.com) and the latest *“Product Selector Guide”* (DS00148) for the complete list of demonstration, development and evaluation kits.

12.3 DC Characteristics: PIC16C712/716-04 (Commercial, Industrial, Extended) PIC16C712/716-20 (Commercial, Industrial, Extended) PIC16LC712/716-04 (Commercial, Industrial)

Standard Operating Conditions (unless otherwise stated)							
Operating temperature $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended Operating voltage V_{DD} range as described in DC spec Section 12.1 “DC Characteristics: PIC16C712/716-04 (Commercial, Industrial, Extended) PIC16C712/716-20 (Commercial, Industrial, Extended)” and Section 12.2 “DC Characteristics: PIC16LC712/716-04 (Commercial, Industrial)”							
Param No.	Sym.	Characteristic	Min.	Typ†	Max.	Units	Conditions
D030 D030A D031 D032 D033	V_{IL}	Input Low Voltage I/O ports with TTL buffer with Schmitt Trigger buffer \overline{MCLR} , OSC1 (in RC mode) OSC1 (in XT, HS and LP modes)	V_{SS} V_{SS} V_{SS} V_{SS} V_{SS}	— — — — —	0.8V 0.15V _{DD} 0.2V _{DD} 0.2V _{DD} 0.3V _{DD}	V V V V V	$4.5\text{V} \leq V_{DD} \leq 5.5\text{V}$ otherwise (Note 1)
D040 D040A D041 D042 D042A D043	V_{IH}	Input High Voltage I/O ports with TTL buffer with Schmitt Trigger buffer \overline{MCLR} OSC1 (XT, HS and LP modes) OSC1 (in RC mode)	2.0 0.25V _{DD} + 0.8V 0.8V _{DD} 0.8V _{DD} 0.7V _{DD} 0.9V _{DD}	— — — — — — —	V _{DD} V _{DD} V _{DD} V _{DD} V _{DD} V _{DD} V _{DD}	V V V V V V V	$4.5\text{V} \leq V_{DD} \leq 5.5\text{V}$ otherwise For entire V _{DD} range (Note 1)
D060 D061 D063	I_{IL}	Input Leakage Current (Notes 2, 3) I/O ports \overline{MCLR} , RA4/T0CKI OSC1	— — —	— — —	±1 ±5 ±5	μA μA μA	$V_{SS} \leq V_{PIN} \leq V_{DD}$, Pin at high-impedance $V_{SS} \leq V_{PIN} \leq V_{DD}$ $V_{SS} \leq V_{PIN} \leq V_{DD}$, XT, HS and LP osc modes
D070	IPURB	PORTB weak pull-up current	50	250	400	μA	$V_{DD} = 5\text{V}$, $V_{PIN} = V_{SS}$

* These parameters are characterized but not tested.

† Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

- Note 1:** In RC Oscillator mode, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC MCU be driven with external clock in RC mode.
- 2:** The leakage current on the \overline{MCLR}/V_{PP} pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.
- 3:** Negative current is defined as current sourced by the pin.

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12.4.2 TIMING CONDITIONS

The temperature and voltages specified in Table 12-1 apply to all timing specifications, unless otherwise noted. Figure 12-3 specifies the load conditions for the timing specifications.

TABLE 12-1: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

	Standard Operating Conditions (unless otherwise stated)
	Operating temperature $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial
	$-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial
	$-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended
AC CHARACTERISTICS	Operating voltage V_{DD} range as described in DC spec Section 12.1 “DC Characteristics: PIC16C712/716-04 (Commercial, Industrial, Extended) PIC16C712/716-20 (Commercial, Industrial, Extended)” and Section 12.2 “DC Characteristics: PIC16C712/716-04 (Commercial, Industrial)” .
	LC parts operate for commercial/industrial temp's only.

FIGURE 12-3: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

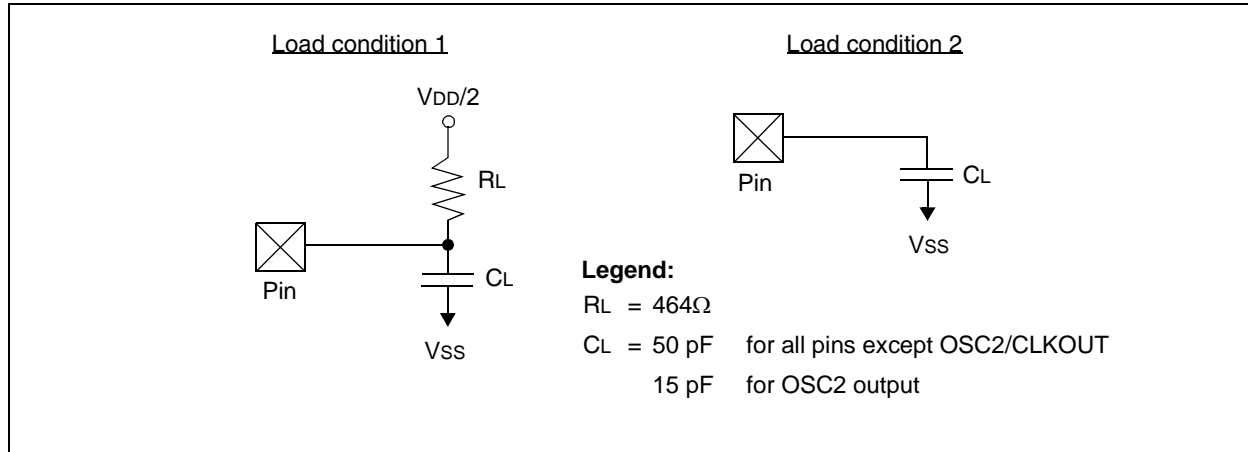


FIGURE 12-10: A/D CONVERSION TIMING

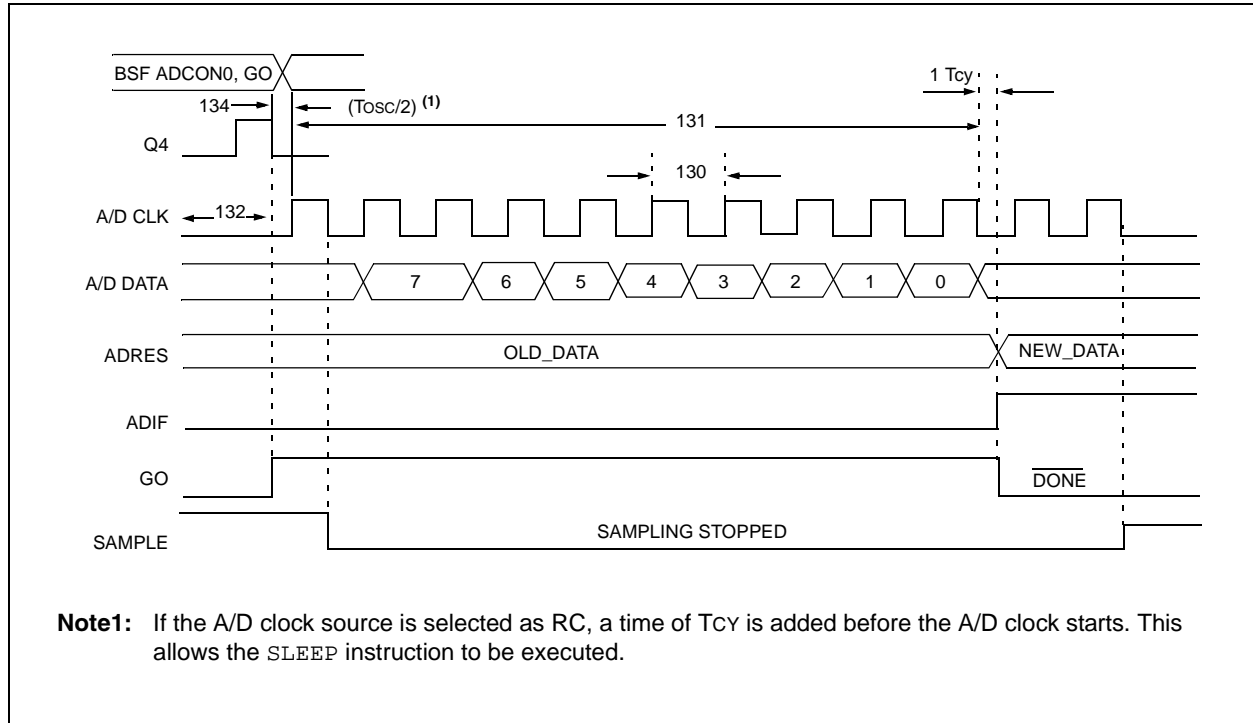


TABLE 12-8: A/D CONVERSION REQUIREMENTS

Param No.	Sym.	Characteristic		Min.	Typ†	Max.	Units	Conditions
130	TAD	A/D clock period	Standard	1.6	—	—	μs	TOSC based, $V_{REF} \geq 3.0\text{V}$
			Extended (LC)	2.0	—	—	μs	TOSC based, V_{REF} full range
			Standard	2.0	4.0	6.0	μs	A/D RC Mode
			Extended (LC)	3.0	6.0	9.0	μs	A/D RC Mode
131	Tcnv	Conversion time (not including S/H time) (Note 1)		11	—	11	TAD	
132	TACQ	Acquisition time		(Note 2)	20	—	μs	The minimum time is the amplifier settling time. This may be used if the “new” input voltage has not changed by more than 1 LSB (i.e., 20.0 mV @ 5.12V) from the last sampled voltage (as stated on CHOLD).
				5*	—	—	μs	
134	Tgo	Q4 to A/D clock start		—	$T_{OSC}/2$ §	—	—	If the A/D clock source is selected as RC, a time of T_{CY} is added before the A/D clock starts. This allows the <code>SLEEP</code> instruction to be executed.
135	Tswc	Switching from convert \overline{AE} sample time		1.5 §	—	—	TAD	

: * These parameters are characterized but not tested.

: † Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

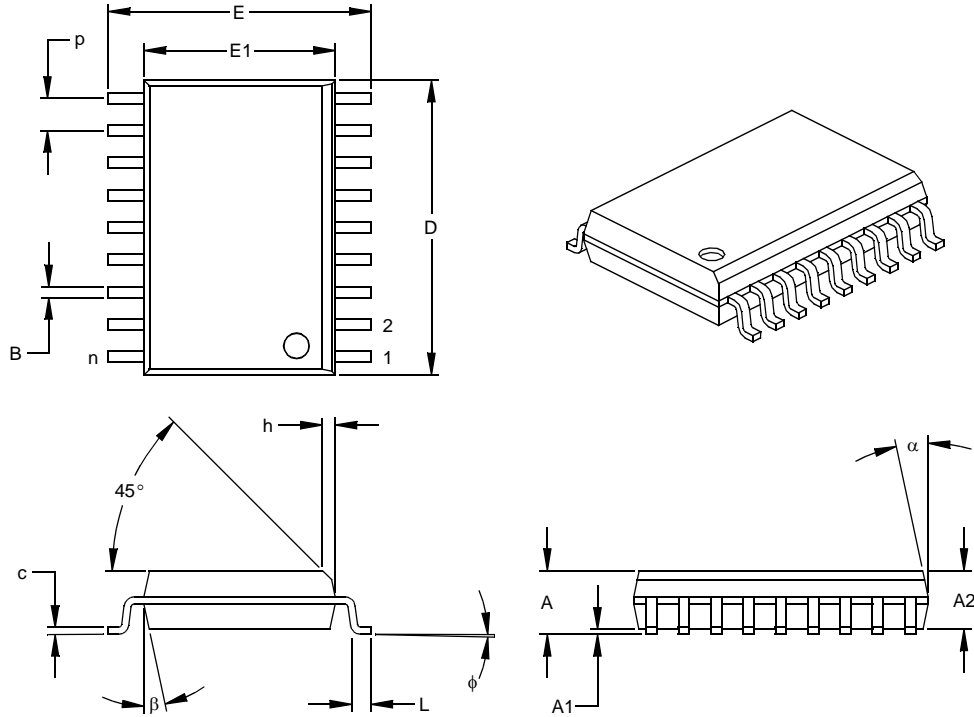
: § This specification ensured by design.

Note 1: ADRES register may be read on the following T_{CY} cycle.

2: See **Section 9.1 “Configuration Bits”** for min. conditions.

18-Lead Plastic Small Outline (SO) – Wide, 300 mil (SOIC)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		INCHES*			MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	P		.050			1.27	
Overall Height	A	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	E	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.291	.295	.299	7.39	7.49	7.59
Overall Length	D	.446	.454	.462	11.33	11.53	11.73
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.009	.011	.012	0.23	0.27	0.30
Lead Width	B	.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter
 § Significant Characteristic

Notes:
 Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.
 JEDEC Equivalent: MS-013
 Drawing No. C04-051

APPENDIX A: REVISION HISTORY

Version	Date	Revision Description
A	2/99	This is a new data sheet. However, the devices described in this data sheet are the upgrades to the devices found in the <i>PIC16C6X Data Sheet</i> , DS30234, and the <i>PIC16C7X Data Sheet</i> , DS30390.
B	9/05	Removed Preliminary Status.
C	1/13	Added a note to each package outline drawing.

APPENDIX B: CONVERSION CONSIDERATIONS

There are no previous versions of this device.

APPENDIX C: MIGRATION FROM BASE-LINE TO MID-RANGE DEVICES

This section discusses how to migrate from a baseline device (i.e., PIC16C5X) to a mid-range device (i.e., PIC16CXXX).

The following are the list of modifications over the PIC16C5X microcontroller family:

1. Instruction word length is increased to 14-bits. This allows larger page sizes both in program memory (2K now as opposed to 512 before) and register file (128 bytes now versus 32 bytes before).
2. A PC high latch register (PCLATH) is added to handle program memory paging. Bits PA2, PA1, PA0 are removed from STATUS register.
3. Data memory paging is redefined slightly. STATUS register is modified.
4. Four new instructions have been added: RETURN, RETFIE, ADDLW, and SUBLW. Two instructions TRIS and OPTION are being phased out although they are kept for compatibility with PIC16C5X.
5. OPTION_REG and TRIS registers are made addressable.
6. Interrupt capability is added. Interrupt vector is at 0004h.
7. Stack size is increased to 8 deep.
8. Reset vector is changed to 0000h.
9. Reset of all registers is revisited. Five different Reset (and wake-up) types are recognized. Registers are reset differently.
10. Wake-up from Sleep through interrupt is added.

11. Two separate timers, Oscillator Start-up Timer (OST) and Power-up Timer (PWRT) are included for more reliable power-up. These timers are invoked selectively to avoid unnecessary delays on power-up and wake-up.
12. PORTB has weak pull-ups and interrupt on change feature.
13. T0CKI pin is also a port pin (RA4) now.
14. FSR is made a full eight-bit register.
15. "In-circuit serial programming" is made possible. The user can program PIC16CXX devices using only five pins: VDD, VSS, MCLR/VPP, RB6 (clock) and RB7 (data in/out).
16. PCON STATUS register is added with a Power-on Reset Status bit (POR).
17. Code protection scheme is enhanced such that portions of the program memory can be protected, while the remainder is unprotected.
18. Brown-out protection circuitry has been added. Controlled by Configuration Word bit BODEN. Brown-out Reset ensures the device is placed in a Reset condition if VDD dips below a fixed setpoint.

To convert code written for PIC16C5X to PIC16CXXX, the user should take the following steps:

1. Remove any program memory page select operations (PA2, PA1, PA0 bits) for CALL, GOTO.
2. Revisit any computed jump operations (write to PC or add to PC, etc.) to make sure page bits are set properly under the new scheme.
3. Eliminate any data memory page switching. Redefine data variables to reallocate them.
4. Verify all writes to STATUS, OPTION, and FSR registers since these have changed.
5. Change Reset vector to 0000h.

PIC16C712/716 PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	-XX	X	/XX	XXX
Device	Frequency Range	Temperature Range	Package	Pattern
Device: PIC16C712 ⁽¹⁾ , PIC16C712T ⁽²⁾ ; VDD range 4.0V to 5.5V PIC16LC712 ⁽¹⁾ , PIC16LC712T ⁽²⁾ ; VDD range 2.5V to 5.5V PIC16C716 ⁽¹⁾ , PIC16C716T ⁽²⁾ ; VDD range 4.0V to 5.5V PIC16LC716 ⁽¹⁾ , PIC16LC716T ⁽²⁾ ; VDD range 2.5V to 5.5V	Frequency Range: 04 = 4 MHz 20 = 20 MHz	Temperature Range: blank = 0°C to 70°C (Commercial) I = -40°C to +85°C (Industrial) E = -40°C to +125°C (Extended)	Package: JW = Windowed CERDIP SO = SOIC P = PDIP SS = SSOP	Pattern: QTP, SQTP, Code or Special Requirements (blank otherwise)
Examples: a) PIC16C716 – 04/P 301 = Commercial temp., PDIP package, 4 MHz, normal VDD limits, QTP pattern #301. b) PIC16LC712 – 04/SO = Industrial temp., SOIC package, 200 kHz, Extended VDD limits. c) PIC16C712 – 20I/P = Industrial temp., PDIP package, 20MHz, normal VDD limits.				
Note 1: C = CMOS LC = Low Power CMOS 2: T = in tape and reel – SOIC, SSOP packages only. 3: LC extended temperature device is not offered. 4: LC is not offered at 20 MHz				

* JW Devices are UV erasable and can be programmed to any device configuration. JW Devices meet the electrical requirement of each oscillator type (including LC devices).

Sales and Support

Data Sheets

Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

1. Your local Microchip sales office
2. The Microchip Worldwide Site (www.microchip.com)

NOTES: